


- NOTES:
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
 2. SEAL AREA TO BE METALLIZED.
 3. DIE ATTACH AREA TO BE METALLIZED.
 4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
 5. LEAD RESISTANCE :
W/B No.1,9,10,20,35,43,52,60 ----0.2 OHM MAX.
THE OTHERS-----1.0 OHM MAX.

MODIFICATION				NAME B9 PIN GRID ARRAY PACKAGE		TOLERANCE UNLESS OTHERWISE SPECIFIED ±.005		DRAWN CHECKED APPROVED DATE	
CHANGED				SCALE 5/1		MATERIAL AS INDICATED		S.N. S.A. T.A. APPLD. BY	
DATE				DRAWN CHECKED APPROVED		KYOCERA CORPORATION KYOTO JAPAN		DRAWING NO. KD-P87279	
								SHEET 1/3	



WIRE BOND PAD / CONNECTOR PIN INTERCONNECTION PLAN

W/B NO.	PIN NO.	W/B NO.	PIN NO.	W/B NO.	PIN NO.	W/B NO.	PIN NO.
1	B2	21	L3	41	G10	61	A6
2	B1	22	K4	42	G11	62	B5
3	C2,C3	23	L4	43	F10	63	A5
4	C1	24	K5	44	F11	64	B4
5	D2	25	L5	45	E10	65	A4
6	D1	26	K6	46	E11	66	B3
7	E2	27	L6	47	D10	67	A3
8	E1	28	K7	48	D11	68	A2
9	F2	29	L7	49	C10		
10	F1	30	K8	50	C11	S/R	NC
11	G2	31	L8	51	B11	D/A	NC
12	G1	32	K9	52	B10		
13	H2	33	L9	53	A10		
14	H1	34	L10	54	B9		
15	J2	35	K10	55	A9		
16	J1	36	K11	56	B8		
17	K1	37	J10	57	A8		
18	K2	38	J11	58	B7		
19	L2	39	H10	59	A7		
20	K3	40	H11	60	B6		

MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						69 PIN GRID ARRAY PACKAGE	UNLESS OTHERWISE SPECIFIED	S.N	S.A	T.A	APR.07.'87
						SCALE	MATERIAL				
	CHANGED	DATE	DRAWN	CHECKED	APPROVED		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO. KD-P87279			SHEET 3/3



